

Title (en)  
LOW DENSITY COMPOSITIONS CONTAINING POLYETHER BLOCK AMIDES AND HOLLOW GLASS REINFORCEMENTS AND USE OF SAME

Title (de)  
ZUSAMMENSETZUNGEN MIT NIEDRIGER DICHT E MIT POLYETHERBLOCKAMIDEN UND HOHLGLASVERSTÄRKUNGEN UND VERWENDUNG DAVON

Title (fr)  
COMPOSITIONS DE POLYETHER BLOCK AMIDES, DE FIBRES DE CARBONE ET DE RENFORTS DE VERRE CREUX PRESENTANT UNE FAIBLE DENSITE ET LEUR UTILISATION

Publication  
**EP 4229114 A1 20230823 (FR)**

Application  
**EP 21810067 A 20211012**

Priority  
• FR 2010535 A 20201015  
• FR 2021051765 W 20211012

Abstract (en)  
[origin: WO2022079380A1] The present invention relates to a moulding composition comprising by weight: (A) 45% to 90%, particularly 60% to 80%, more particularly 62.5% to 77.5% of at least one copolyamide with amide units (Ba1) and polyether units (Ba2); (B) 5% to 30%, particularly 10% to 20%, more particularly 12.5% to 17.5% of carbon fibres; (C) 5% to 20%, particularly 10% to 15% of a hollow glass reinforcement; and (D) 0 to 5%, preferably 0.1% to 2% of at least one additive; the sum of the proportions of each constituent (A) + (B) + (C) + (D) of the composition being equal to 100%.

IPC 8 full level  
**C08G 69/40** (2006.01); **C08K 7/06** (2006.01); **C08K 7/28** (2006.01)

CPC (source: EP KR US)  
**C08G 69/40** (2013.01 - EP KR US); **C08K 3/04** (2013.01 - KR); **C08K 7/06** (2013.01 - EP KR US); **C08K 7/28** (2013.01 - EP KR US); **C08L 77/02** (2013.01 - KR); **C08K 2201/003** (2013.01 - EP US)

Citation (search report)  
See references of WO 2022079380A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

Designated validation state (EPC)  
KH MA MD TN

DOCDB simple family (publication)  
**WO 2022079380 A1 20220421**; CN 116348533 A 20230627; EP 4229114 A1 20230823; FR 3115285 A1 20220422; FR 3115285 B1 20231117; JP 2023546130 A 20231101; KR 20230087529 A 20230616; US 2023399466 A1 20231214

DOCDB simple family (application)  
**FR 2021051765 W 20211012**; CN 202180070925 A 20211012; EP 21810067 A 20211012; FR 2010535 A 20201015; JP 2023523071 A 20211012; KR 20237015691 A 20211012; US 202118248926 A 20211012